



Some selected in situ characterization tools for MBE growth and their complementarity

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- > In-situ control of growth: a global approach
- > An example structure: the growth of VCSELs
- > Focus on some instruments
 - RHEED
 - Reflectivity
 - Atomic Absorption Spectroscopy for direct flux measurement
 - Band Edge Thermometry for reproducible wafer temperature evaluation
 - Wafer Curvature and stress management
- > Complementarity
 - For alloy concentration/growth rates
 - In time scales
- > Towards automation of MBE growth
 - Bragg mirror automatically grown thanks to spectral reflectivity
 - Automated lattice match control of alloys growth
 - Monitoring MBE substrate deoxidation and surface reconstruction change via RHEED image-sequence analysis by deep learning
- > Conclusions





Issues: growth of complex materials



Ex-situ post-growth tools (XRD, SEM, (HR)TEM, PL, ...)



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Coupled In situ and **real-time** diagnostics (stress, reflectivity, surface morphology, flux monitoring...)

No diagnostic tool provide a complete picture of the growth process, but coupling them in the same time base maximize their **complementarity**



In-situ measurements at LAAS

A global approach: complementary tools to get a clear picture of growth processes



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MBE412 - 4" III-V chamber

Spectral reflectivity

- White light source
- CCD sensors



> Temperature

- Band-Edge Thermometry
- Pyrometry
- > Fluxes (Atomic absorption Spectroscopy OFM)
 - Original tool (Patent FR1856743)
- > RHEED: synchronised to rotation
 - In-plane lattice parameter, streaks intensity
- Roughness (Diffuse Light Scattering)

> Curvature

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• MIC : original tool (Patent FR175461)



In-situ measurements at LAAS

A global approach: complementary tools to get a clear picture of growth processes



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- > Spectral reflectivity
 - White light source
 - CCD sensors



Several tools

- synchronized to rotation
- in the same time base
- Inked to MBE control software
 - > Roughness (Diffuse Light Scattering)
 - > Curvature

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• MIC : original tool (Patent FR175461)

MBE412 - 4" III-V chamber

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Geometric configuration



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MBE412 - 4" III-V chamber





An example structure: the growth of VCSEL







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> MBE solid-sources are not very stable

- Flux transients when cell opening can be >10% of the nominal flux
- Flux drifts due to effusion cells depletion

AI5 ABN150DF AI12 ABN150DF 3a cell temperature (°C) Al cell temperature (°C) 1532 1530 1552 1552 Ga6_ABN300DF Ga11 ABN300DF Growth run Growth run

Cells equivalent temperature for $1 \,\mu$ m/h growth rate over VCSEL run

. . .





Focus on some instruments





In situ characterization tools in MBE: Reflectivity

In-situ characterization tools: *RHEED*

(Reflection High Energy Electron Diffraction)







Diffraction pattern

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- Surface morpholgy
 - Reconstruction (V/III ratio, temperature, ...)
 - Roughness (2D-3D growth, ...)
- Growth rate



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I. Hernandez-Calderon, H. Höchst, Phys. Rev. B 27 (1983) 4961





Roughness (2D-3D growth, ...)

M.A. Hafez, M.K. Zayed, H.E. Elsayed-Ali Geometric interpretation of reflection and transmission RHEED patterns Micron, 159 (2022), Article 103286

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GaAs (001) Ideal surface

As

Ga





GaAs (001) β 2(2x4) surface reconstruction









Live RHEED

GaAs (001) β 2(2x4) surface reconstruction





Image capture synchronized to rotation One image every 2π/n (n=2, 4, ...)







Live RHEED

GaAs (001) β 2(2x4) surface reconstruction



[110] [1-10]











Live RHEED

GaAs (001) β 2(2x4) surface reconstruction



Surface phase diagram for GaAs(001) growth from Ga and As₄



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L. Däweritz, R. Hey Surf. Sci. 236, 15(1990)



GaAs (001) - T = 580° C - 12 rpm β 2(2x4) surface reconstruction





Get intensity profiles for each rotation angle

GaAs (001) - T = 580° C - 12 rpm β 2(2x4) surface reconstruction





GaAs (001) - T = 580° C - 12 rpm β 2(2x4) surface reconstruction

W. Braun, Applied RHEED, Springer (1999) Paul Drude Institute Berlin / iRHEED website

Surface reconstruction / crystal phase

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GaAs (001) - T = 580° C - 12 rpm β 2(2x4) surface reconstruction

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Surface reconstruction / crystal phase

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At LAAS – rotation at 4 rpm GaAs (2x4) surface reconstruction





BiSbTe on Si (111) $(\sqrt{3} \times \sqrt{3})$ surface

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Courtesy S. P. Plissard – LAAS-CNRS



RHEED can also be used to calibrate growth rate, provided that

- No rotation (!)
- Substrate is small to reduce non homogeneity of growth rate along its surface (~1 cm²)



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https://www.youtube.com/watch?v=NMTsd9D8vAM



RHEED specular sport intensity oscillations over time $rac{1}{2}$ growth rate







In situ characterization tools in MBE: Reflectivity

In-situ characterization tools: *Reflectivity*








Optical index evolution with Al concentration and temperature



Data:

M.A.A. Afromovitz, *Solid State Commun. (USA)*, **15**, pp59-63 (1974) K.P. O'Donnell, *Appl. Phys. Lett.* **58**, 2924 (1991)















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Spectral reflectivity during the growth of a Bragg mirror



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EZ-REF software developed within EpiCentre joint lab











Real-time growth rate and refractive index determination of multiple layers



EZ-REF VIS2NIR Spectra

EZ-REF 🔶

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Reflectivity spectra of a complete VCSEL structure





Real-time stop-band center determination of Bragg mirrors





Real-time Fabry-Perot dip position determination (VCSELs)



Spectral reflectivity is a powerful instrument able to

- Help calibrating growth rates
- Follow some optical features in real-time
- Check early in the growth that everything goes as expected





In-situ characterization tools: *Atomic Absorption*









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In-situ characterization tools: Band Edge Thermometry



In situ characterization tools in MBE: Band Edge



In situ characterization tools in MBE: Band Edge



BET temperature oscillates when growing different materials



In situ characterization tools in MBE: Band Edge



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In situ characterization tools in MBE: Band Edge

Possibility to map wafer temperature



0 50 4" (100mm) 40 30 588,0 587,0 20 586.0 10 Position (mm) 585,0 0 - 270 90 584,0 583,0 10 582,0 20 581,0 580.0 30 $\Delta = 8^{\circ}C$ 40 50









- > Rather than an **absolute** temperature, BET provides a reproducible temperature independent of experimental conditions (same from MBE chamber to MBE chamber, stable over the long term, etc.)
- > The interest for materials whose growth is very sensitive to temperature (GaAsBi, CdHgTe, etc.) is obvious
- > What about complex GaAs/AlGaAs-based structures (VCSEL - QCL)?





In-situ characterization tools: Curvature



Stress measurement: how ?

> There are two mains ways to measure curvature in situ and in real-time:

- Laser deflection
 - kSA MOS
 - Laytec EpiCurve®TT

https://k-space.com/product/mos/	

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Stress measurement: how ?

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Magnification Inferred Curvature (MIC)
Riber EZ-CURVE®

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> There are two mains ways to measure curvature in situ and in real-time:

Laser deflection

- kSA MOS
- Laytec EpiCurve®TT

Magnification Inferred Curvature (MIC)

Riber EZ-CURVE®

Robust and sensitive technique (thick wafers, rotation (=wobbling), MBE environment, ...)



Curvature/stress measurement: MIC

MIC (Magnification Inferred Curvature)







Curvature/stress measurement: MIC

MIC (Magnification Inferred Curvature)



Arnoult, A., Colin, J. Magnification inferred curvature for real-time curvature monitoring. *Sci Rep* **11**, 9393, 2021 https://doi.org/10.1038/s41598-021-88722-6

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Curvature: MIC theory

MIC (Magnification Inferred Curvature) **analytical equations whatever the incidence angle:**



Arnoult, A., Colin, J. Magnification inferred curvature for real-time curvature monitoring. *Sci Rep* **11**, 9393 2021) https://doi.org/10.1038/s41598-021-88722-6

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In situ characterization tools in MBE: Curvature

Virtual image magnification analysis: MIC (Magnification Inferred Curvature) measures the magnification factor of a virtual image created by a surface (i.e. a wafer)







Curvature and stress are linked

> Usually, **three stress components** are distinguished:

Extrinsic stress

Induced by external factors: external loading, exposure to environment, ...


Stress/Curvature and crystal growth

Extrinsic stress





Wafer free to expand in holder \Rightarrow no <u>extrinsic</u> stress here





> Usually, **three stress components** are distinguished:

Extrinsic stress

Induced by external factors : external loading, exposure to environment, ...

2. Intrinsic stress

 Stress source introduced during the MBE process : lattice mismatch, growth mode, relaxation, surface and/or interface stress, incorporation or desorption of impurities, phase transformations...





- > Usually, **three stress components** are distinguished:
- Extrinsic stress here
 Induced by extended by extende



Intrinsic stress

 Stress source introduced during the MBE process : lattice mismatch, growth mode, relaxation, surface and/or interface stress, incorporation or desorption of impurities, phase transformations...





- > Usually, **three stress components** are distinguished:
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Intrinsic stress

Stress source introduced during the MBE process : <u>lattice mismatch</u>, growth mode, relaxation, surface and/or interface stress, incorporation or desorption of impurities, phase transformations...



In situ characterization tools in MBE: Curvature

Why thin films are usually in a stressed state?



The stress in the film leads to a bending of the system "film+substrate"

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AAS CNRS In situ characterization tools in MBE: Curvature



- $\sigma_{\rm f}$ = stress in the film
- Satisfying equilibrium conditions ($\Sigma F = 0$ and $\Sigma M = 0$) leads to the **Stoney equation**

 $\cong \frac{6\overline{\sigma_f}h_f}{M_s h_s^2}$ with $Ms = \frac{E}{1 - v}$ **κ** = Stoney

G.G. Stoney, The tensions of metallic films deposited by electrolysis, Proc. R. Soc. Land. A82 (1909) 172-175









1000

Thickness hf (nm)

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1500

-6

-8

-10

0

500

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MBE growth of GaAs/AlGaAs on a rotating

350 µm-thick (001) GaAs wafer at 600°C

Intrinsic stress

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Intrinsic stress



Intrinsic stress

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Intrinsic stress



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Intrinsic stress



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- > Usually, **three stress components** are distinguished:
- Extrinsic stress here
 Induced by externa Induced by externa

2. Intrinsic stress

Stress source introduced during the MBE process : <u>lattice mismatch</u>, growth mode, relaxation, surface and/or interface stress, incorporation or desorption of impurities, phase transformations...

Thermal stress

Difference in <u>thermal expansion coefficients</u> between film and substrate



Stress/Curvature and crystal growth

Thermal stress

> > Because thermal expansion coefficient is material dependent, any change in temperature induces a change in stress/curvature of an heteroepitaxial stack.



Stress/Curvature and crystal growth

Thermal stress

> > Because thermal expansion coefficient is material dependent, any change in temperature induces a change in stress/curvature of an heteroepitaxial stack.



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MIC Robustness to substrate rotation: anisotropy



Wafer : Single-side polished GaAs NID AXT (001) 50mm diameter 350µm thick Measured at 580C Rotation : 12RPM

Because **substrate is rotating**, it is possible to measure the curvature in any direction, and to get a clear view of its shape **in live**

Note : It is also possible to measure this complete shape on non-rotating substrates at normal incidence

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In situ characterization tools in MBE: Curvature



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Ex-situ characterization of full wafer shape





100mm GaAs wafer + VCSEL growth

See www.dip-view.com



In situ characterization tools in MBE: Curvature

MIC : some experimental results

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Tunnel jonctions for solar cells



Real-time observation of relaxation

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Complementarity for alloy concentration / growth rate measurement





> Stoney equation:

 $\kappa \approx \frac{6\overline{\sigma_f}h_f}{M_s h_s^2} = 6\frac{h_f}{h_s^2}\frac{M_f}{M_s}\varepsilon = -6\frac{h_f}{h_s^2}\frac{M_f}{M_s}\frac{a_f - a_s}{a_s} \qquad \text{Avec } M = \frac{E}{1 - \nu}$



Young Modulus



Compositional dependence of the elastic constants and the lattice parameter of AlGaAs Gehristz et al. PRB 60 (16), 1999

$$a_f = a_{AlGaAs} = xa_{AlAs} + (1 - x)a_{GaAs}$$

$$\kappa \approx -\frac{6h_{AlGaAs}}{{h_s}^2} \times x \times \frac{a_{AlAs}(T) - a_{GaAs}(T)}{a_{GaAs}(T)}$$



Growth rate: Curvature

$$k \approx -\frac{6h_{AlGaAs}}{{h_s}^2} \times x \times \frac{a_{AlAs}(T) - a_{GaAs}(T)}{a_{GaAs}(T)}$$
$$\frac{\Delta \kappa}{\Delta t} \approx -\frac{6 \times G_{AlAs}}{{h_s}^2} \times \frac{a_{AlAs}(T) - a_{GaAs}(T)}{a_{GaAs}(T)}$$

with
$$h_{AlGaAs} = G_{AlGaAs} \times t$$

= $(G_{GaAs} + G_{AlAs}) \times t$
 $x = \frac{G_{AlAs}}{G_{GaAs} + G_{AlAs}}$



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Reflectivity – Curvature complementarity



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Spectral reflectivity



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Amplitude

Spectral reflectivity



RF

RENATEC

NATE

Amplitude

Spectral reflectivity

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RENATECI

Spectral reflectivity

AAS



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Spectral reflectivity





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Complementarity and time scales

> Reflectivity, Atomic Absorption and Curvature adress different time scales / thicknesses

	Reflectivity	Curvature	Atomic Abs.
10H / 10µm	+++	+++	+
1H / 1µm	++	+++	+
Minutes / 10 th nm	-	++	++
Seconds / ml	x	+	+++





Towards automation of MBE growth





Bragg mirrors automatically grown thanks to spectral reflectivity



Bragg mirrors automatically grown



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Auto-DBR growth: Experiment





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Auto-DBR growth: Primary Results





FTIR measurement of 5 periods auto-DBR and comparison with expected

 \rightarrow Phase compensation effect

 \rightarrow Good control of the centering wavelength





Automated lattice match control of alloys growth



MIC (Riber EZ-CURVE) and Crystal XE



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https://www.ez-curve.com/

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Automatic lattice match control of a 730 nm-thick InGaAs on InP

Rotating substrate:

- (001) InP
- 50 mm dia.
- 400 µm thick



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Automatic lattice match control of a 730 nm-thick InGaAs on InP

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Rotating substrate: Automatic lattice match control of a 730 nm-thick InGaAs on InP (001) InP 50 mm dia. 400 µm thick 0.73 µm InGaAs on InP HRXRD 107 InGaAs growth Cooling down. 12 908 10⁶ InP substrate 10 907 In_{0.522}Ga_{0.478}As layer 8 Counts per second 10⁵ 906 6 ပိ ပိ stress cell temperature 905 10⁴ 2 904 0 10³ -2 Manual Manual Manual Manual Manual 903 -4 10² <u>_</u> -6 902 -8 10 901 ≥ 20°C 20°C 500°C -10 -12 900 10⁰ 1800 0 3600 5400 62.5 63.0 63.5 64.0 Growth time (s) **2**θ (°) PID loop on indium cell (set on curvature change) Thermal expansion coefficients mismatch

thermal stress

Curvature (km⁻¹)



Automatic lattice match control of a 730 nm-thick InGaAs on InP



Automatic lattice match control of a 730 nm-thick InGaAs on InP



Bisaro et al, Appl. Phys. Lett. **34**(1), 100 (1979)

- $\alpha_{\text{ln}_{0.53}\text{Ga}_{0.47}\text{As}} = (5.55 \pm 0.10) \times 10^{-6} / \text{°C}$
- α_{InP} = (4.56 ± 0.10) x 10⁻⁶ / °C

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Automatic lattice match control of a 730 nm-thick InGaAs on InP

Rotating substrate:

- (001) InP
- 50 mm dia.
- 400 μm thick



PID loop on indium cell (set on curvature change)





PID loop on indium cell (set on curvature change)



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- > Magnification Inferred Curvature (MIC) makes it possible to <u>control automatically</u> the lattice parameter of the growing layer in MBE
- > Thermal expansion needs to be considered in order to reach a perfect after-growth lattice match
- Sector States States





Monitoring MBE substrate deoxidation and surface reconstruction change via RHEED image-sequence analysis by deep learning



Surface deoxidation and AI

Native oxide removal



Plach et al, Journal of Applied Physics 2013, 113

- Slowly heating the subtrate
- Detect deoxydation moment
- Stop heating to avoid damaging the crystal

oxidized surface



deoxidized surface





Courtesy A Khaireh Walieh – LAAS-CNRS



Neural network architecture



Khaireh-Walieh et al, Crystal Growth & Design 2023, 23, 2, 892-898

dataset of 7644 images $\begin{cases} 80\% \text{ for training} \\ 20\% \text{ for validation} \end{cases}$

Surface deoxidation and AI

Test with a set of images captured during the entire deoxidation procedure and varying the sequence length as well as the latent space size.



Khaireh-Walieh et al, Crystal Growth & Design 2023, 23, 2, 892-898



Surface reconstruction: (2×4) and $c(4 \times 4)$



Penev et al, Physical review letters 2004, 93, 14, 146102

- Rearrangement of surface atoms
- Depending on the growing conditions

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• Inter-atomic forces only from the bulk side

(2x4)



c(4x4)



RHEED patterns

model overview



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3150 images $\begin{cases} 85\% \text{ for training} \\ 15\% \text{ for validation} \end{cases}$

Courtesy A Khaireh Walieh – LAAS-CNRS

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Neural network architecture



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Courtesy A Khaireh Walieh – LAAS-CNRS

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Model test

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Test with images captured during surface transition: $c(4 \times 4)$ to (2×4) .



Model test

CNRS

Test with images captured during surface transition: (2×4) to $c(4 \times 4)$





- AI make it possible to monitor automatically complex processes that only trained users can detect
- > Work in progress





 In situ and real-time instruments address complementary information

 Substrate temperature, growth rates, growth modes, surface geometry, ... can be analyzed in real time

Different time scales can be monitored

- Coupling in-situ tools
 - \rightarrow Further understanding of the growth mechanisms

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 Control of growth and properties of epitaxial materials and device structures







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